GN04022N

GaAs N-Channel IC

For W-CDMA

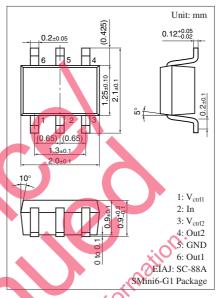
For high-frequency and high-power SPDT switch

■ Features

- Low insertion
- High isolation
- S-Mini type 6-pin package

■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit
Supply voltage	V_{DD}	8	V
Control current	$V_{ctrl(H)}$ - $V_{ctrl(L)}$	+6	v
Maximum input power	P _{IN}	35	dBm
Operating ambient temperature	T _{opr}	-30 to +90	°C
Storage temperature	T _{stg}	-40 to +120	°C



Marking Symbol: LV

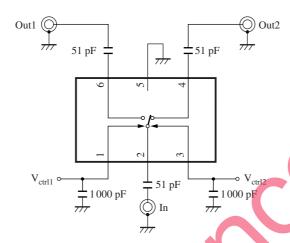
■ Electrical Characteristics $V_{ctrl(L)} = 0$ V, $V_{ctrl(H)} = 3.0$ V, f = 1920 MHz to 2170 MHz, $T_a = 25$ °C ± 3 °C

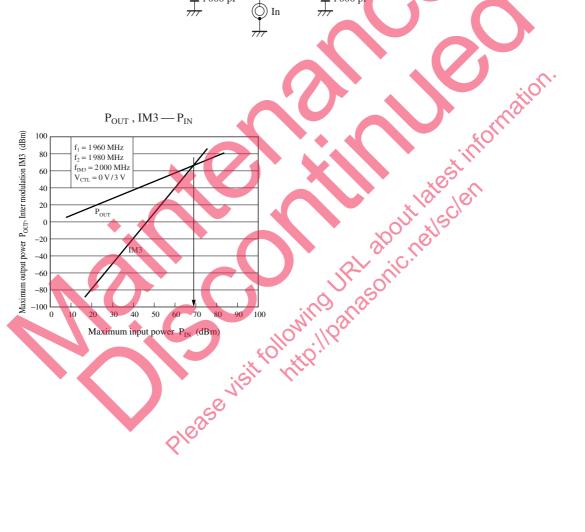
Parameter	Symbol	Conditions	Mih)	Тур	Max	Unit
Insertion loss	IL	In-Out1, $P_{IN} = 26 \text{ dBm}$		0.25	0.45	dB
		In-Out2, $P_{IN} = 26 \text{ dBm}$		0.25	0.45	
Isolation	ISO	In-Out1 (In-Out2 on)	21	23		dB
		In-Out2 (In-Out1 on)	21	23		
Voltage standing wave ratio *	VSWR	In-Out1, 2		1.10	1.30	dB
Input 0.1 dB Compression	P _{IN(P0.1 dB)}	V _{ctrl(H)} =3V	30	31		dBm
Input 1 dB Compression*	P _{IN(P1.0 dB)}	$V_{c(rl(H))} = 3 \text{ V}$	32	33		dBm
Control current	I_{ctrl}	In-Out 1, 2		1	9	μΑ

Note) *: Designed specification

GN04022N GaAs MMIC

■ Measurement Circuit





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SGB00019AED



■ This product contains Gallium Arsenide (GaAs).

GaAs powder and vapor are hazardous to human health if inhaled or ingested. Do not burn, destroy, cut, cleave off, or chemically dissolve the product. Follow related laws and ordinances for disposal. The product should be excluded from general industrial waste or household garbage.

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